

**In the claims:**

**Claim 1** (currently amended)      A tin-silver based lead-free solder, containing 0.3 to 1% by weight of zinc (Zn) added to a solder, consisting of ~~comprising~~ a tin-silver system containing no lead.

**Claim 2** (currently amended)      The A tin-silver based lead-free solder ~~of claim 1,~~ containing 0.3 to 1% of zinc further containing indium (In) added thereto.

Cancel **Claim 3.**

**Claim 4** (currently amended)      The tin-silver based lead-free solder of claim 2, containing less than 10% by weight of indium (In) and 0.1 to 1.0% by weight of zinc (Zn) and the remainder is tin and silver.

**Claim 5** (previously presented)      A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 1.

**Claim 6** (previously presented)      The joint structure of claim 5, wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

**Claim 7** (currently amended)      The joint structure of claim 6, wherein said electroless plating layer is a Ni-P plating.

Please add the following claims:

**Claim 8 (new)**      A solder of claim 1 containing 3.5% by weight of silver.

**Claim 9 (new)**      A solder of claim 2 containing 3.5% by weight of silver.

**Claim 10 (new)**      A solder of claim 2 wherein the amount of indium is at least 8% by weight.

**Claim 11 (new)**      A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 2.

**Claim 12 (new)**      The joint structure of claim 5 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

**Claim 13 (new)**      The joint structure of claim 11 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

**Claim 14 (new)**      The joint structure of claim 11 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

**Claim 15 (new)**      The joint structure of claim 12 wherein said electrodes plating layer is a Ni-P plating.

**Claim 16 (new)**      The joint structure of claim 11 wherein said electrodes plating layer is a Ni-P plating.